Funding opportunity

NSERC-National Science and Technology Council of Taiwan (NSTC) call for proposals on semiconductors and artificial intelligence

Partners

This call aims to support collaborative bilateral research projects and is jointly funded by the Natural Sciences and Engineering Research Council of Canada (NSERC) and the National Science and Technology Council of Taiwan (NSTC).

Notice

The official national call announcement for Taiwanese researchers has been released on the NSTC website (https://www.nstc.gov.tw/sci/ch) (In Chinese only). Comprehensive information regarding the call and application procedures is provided on the homepage of the coordinating funding agency, NSERC, under the program entitled "NSERC-NSTC call for proposals on semiconductors and artificial intelligence."

NSERC is the lead agency for this call and is responsible for receiving and evaluating the proposals submitted by the Canadian PI on behalf of both the Canadian and the Taiwanese teams. In parallel, the Taiwanese Principal Investigators (PI) are required to submit all documents to NSTC in accordance with the procedures of NSTC.

For inquiries from researchers in Taiwan, please refer to the contact information provided below. Interested applicants are advised to consult the NSTC website for detailed guidelines and further information.

Grant Subsidy Items

The grant subsidy items shall be implemented in compliance with the NSTC Directions for Research Project Subsidization.

Application Method, Time, and Execution Period

Application Limitation

Each Taiwanese PI is permitted to submit only one application under this special project; however, serving as a co-PI on other applications is not restricted.

Eligible Principal Investigators

All NSTC applicants must meet the eligibility requirements of the NSTC Directions for Research Project Subsidization.

Application Procedure and Timeline

The Project opens for applications on the date of the official Call for Proposals. Applicants must complete the online submission of their research proposals in accordance with the provisions of the NSTC Directions for Research Project Subsidization, and within the timeframe specified by their respective institutions. Applications must be reviewed and approved by the applicant institutions prior to submission. The application roster and the statement of PI eligibility must be duly reviewed and stamped by the relevant institutional personnel before submission to the NSTC.

Maximum Value per Project

TWD $5,400,000 in total for three years

Joint Submission Requirements

The Participants intend that a single Letter of Intent (LOI) and full collaborative research proposal (if invited) will be submitted to NSERC by the Canadian PI on behalf of the international team. The LOI, as well as the full proposal, must comply with the specific requirements and submission guidelines outlined in the NSERC program documentation.

In parallel, the Taiwanese PI must submit a copy of the LOI that was submitted to NSERC to NSTC via the NSTC online system by March 27, 2026, 5:00 p.m. (Taipei time).

LOIs and full proposals involving Taiwanese applicants that are not submitted on time through the NSTC system will be deemed ineligible. Please carefully follow the instructions below for submission.

Please also note

- Deadline for NSTC System Submission of LOI: 27 March 2026
- Deadline for NSTC System Submission of Full Proposal: 1 August 2026
- Research Project Type: Individual Research Project
- Title and Summary: Translation into Traditional Chinese is not required. Please copy and paste the English title and summary into the fields designated for Traditional Chinese.

Document Submission

All documents submitted through the NSERC online system (by Canadian PI) must also be uploaded to the NSTC online system (by Taiwanese PI).

Scope

Projects submitted under this call must directly address the intersection of AI and semiconductors. Proposals should focus at least on one of the following areas of research:

- Embedding AI across design, manufacturing, packaging：
  - Edge-AI Chip Design
  - AI Chips for Emerging Application, such as Robotics/Drone/Automotive Solutions
  - System integration and novel interconnects for advanced packaging in high-performance computing AI chips
  - Electronic Design Automation, AI-assisted EDA: algorithms and tools
  - Technology Computer-Aided design, TCAD
- Compound semiconductors for AI technologies
- AI technologies in Micro-Electro-Mechanical Systems (MEMS) sensors

Execution and Evaluation

The contract signing, fund disbursement, project extension or modification, fund settlement, and report submission for this project shall be conducted in accordance with the NSTC Directions for Research Project Subsidization, the NSTC Principles for Handling Research Project Grants, the Directions for Subsidized Research Project Report Review, the Research Project Grant Contract, the Research Project Execution Agreement, and other relevant regulations.

Miscellaneous Provisions

No appeal mechanism is available for this project. Any matters not addressed in these guidelines shall be handled in accordance with the NSTC Directions for Research Project Subsidization and other applicable regulations.

Contact Point

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